4<sup>th</sup> Atlas/NIST Workshop on Photovoltaic Materials Durability



# Fragmentation test for crack propensity evaluation of PV backsheets

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## Backsheet cracking in the field modules

\*Microcracks in polyamide backsheet (Western China)



 $30 \ \mu m$ 

\*\*Hairline cracks in polyamide backsheet (China, humid subtropical)



 Various sizes in backsheets

engineering

\*\*\*Cracks in polyester based backsheet (Eastern Spain)



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**Standards and Technology** U.S. Department of Commerce \*Felder et al. SPIE (2014), \*\*Fairbrother et al. SPIE (2017), \*\*\*Gambogi et al. EUPVSC (2013)

# Backsheet cracking from Indoor and outdoor tests



engineering

C	Dutdoor
Field modules	<ul> <li>Yellowing</li> <li>Cracking of Outer layer</li> <li>Delamination of Outer layer</li> </ul>

- Backsheet cracking in field modules
  - ✓ Loss of physical protection
  - ✓ Electrical insulation

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UV exposure of backsheet	Yellowing
Damp Heat of backsheet	Yellowing
Damp Heat of modules	Cracking
UV/Thermal cycling of modules	<ul><li>Yellowing</li><li>Cracking</li></ul>

• Backsheet cracking within the modules in hot environment

Gambogi et al. IEEE J. Photovoltaics, 935 (2014)

#### \*Strain level for cell gap width during thermo-Mechanical Test of PV Modules

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\*U. Eitner et al. (2011) Book chapter in Shell-like structures

### Key research objectives



- Develop test methodology to understand cracking behaviors for PV backsheets, and extend to address backsheet failure in field PV modules
  - ✓ First step: Measuring crack formation in accelerated test conditions (time, temperature, mechanical elongation)



# Accelerated tests (UV, Humidity, Temp.) With mechanical stress

#### With mechanical stress **simultaneously**



Loading Jig

**UV** exposure under mechanical stress

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UV exposed PET film at 23 °C (Confocal microscopy)



tension



With tension  $(\approx 2\% \text{ strain})$ 



### **Experimental conditions**

Material: Polyamide backsheet

Aging conditions: Xenon arc with 65 °C/20%RH for 250 h, 500 h, 1000 h, 2000 h, 4000 h

Mechanical measurements:

- Fragmentation test for backsheet
- AFM (DMT modulus)

Spectroscopic measurements:

- FT-IR (oxidation index)
- Fluorescence (visual inspection)



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# Fragmentation test results for UV exposed Polyamide backsheets



 Lower number of cracks for the 2000 h sample at the saturation strain compared to 500 h and 1000 h samples

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 Lower critical strain (the first crack formation) for the 2000 h sample compared to the 500 h and 1000 h samples



# Depth profiles in the cross-section of Polyamide backsheets

Fluorescence images

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#### Confocal microscopic images



 Spectral changes of fluorescence on the exposed surfaces become deeper with times (i.e. deeper crack)

# Depth profiles in the cross-section of Polyamide backsheets (Oxidation & Stiffness)



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 Higher oxidation on the exposed sides of the cross-sections (suggesting chain scissions) engineering

For the UV exposed side of the cross-sections,

- Higher oxidation
- Higher fluorescence intensity
- Higher modulus

Similar oxygen diffusion rates between 2000 h and 4000 h

# Using fragmentation data for polyamide backsheets (Strength and Crack density for degraded layer

Confocal microscope images



Film strength ( $\sigma_{str}$ ) in film/substrate systems

$$\sigma_{str} = \frac{E_f}{(1 - v_f)} \left[ \frac{(1 - v_f v_s) \dot{\varepsilon}_c}{(1 + v_f)} \right]$$

 $E_f$ : Film modulus,  $v_f$ : Poisson ratio of film  $v_f$ :Poisson ratio of substrate  $\varepsilon_c$ : Critical strain (strain for the first crack)

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#### Crack density at a strain in film/substrate systems

 $1 e^{2\alpha l} - e^{-2\alpha l} + 4\alpha l$ 

$$\frac{\varepsilon_a}{\varepsilon_c} = \sqrt{\frac{3}{2R}}$$
$$\Rightarrow \varepsilon_c = 4 \tanh\left(\frac{\alpha l}{\alpha}\right) - \frac{e^{\alpha l} - e^{-\alpha l} + 2\alpha l}{1 + 2\alpha l} - 2 \tanh(\alpha l) + \frac{1}{2\alpha l} + \frac$$

Where, 
$$\alpha l = \left[\frac{2}{3\beta(1+v_s)}\left(\frac{1}{\beta} + \frac{(1-v_f^2)E_s}{(1-v_fv_s)E_f}\right)\right]^{1/2} \times \frac{1}{t}$$
 and  $\beta = \frac{s}{t}$ 

t: thickness of the exposed layer s: effective substrate thickness  $\varepsilon_c$ : Critical strain (strain for the first crack)  $\overline{l}$ : average space between the cracks

[Hsueh and Yanaka, J. Mater. Sci. pp1809 (2003)]



- Lower strengths than the bulk backsheet strengths
- Strength reductions on the exposed surface compared to the bulk backsheet strengths

Standards and Technology U.S. Department of Commerce  No significant change for the bulk backsheet strengths

#### Applications of fragmentation data for polyamide backsheets (Crack density predictions for degraded layer)



- Measured crack densities ≈
   Predicted crack densities
- Lower crack density for the 2000 h sample (possibly due to deeper crack formations through the thickness)

## Summary



- Critical strains of the polyamide backsheets showing the first cracks decreased with increasing the exposure times
- Strengths and crack densities of the exposed surface layers decreased with increasing the exposure times
- Highest oxidation indexes, fluorescence intensities, and modulus on the exposed sides were observed, and gradually decreased with the thickness of the depth



